

## Addendum

HC908JB16AD/D  
Rev. 1, 8/2002

Addendum to  
MC68HC908JB16  
Technical Data

This addendum provides update and additional information to the  
*MC68HC908JB16 Technical Data, Rev. 1*  
(Motorola document number MC68HC908JB16/D),

pertaining to the following:

- MC68HC908JB16
  - Update to  $V_{REG}$  LVI trip point
  - 20-pin SOIC package
- MC68HC908JB12
- MC68HC08JB16

## MC68HC908JB16

This section updates data sheet information and introduces the 20-pin SOIC package for the MC68HC908JB16.

**$V_{REG}$  LVI Trip Point** Page 318, entry for minimum  $V_{REG}$  LVI trip point voltage has been updated.

*From:*

Characteristic	Symbol	Min	Typ	Max	Unit
$V_{REG}$ LVI trip point voltage	$V_{LVR}$	2.0	2.2	2.6	V

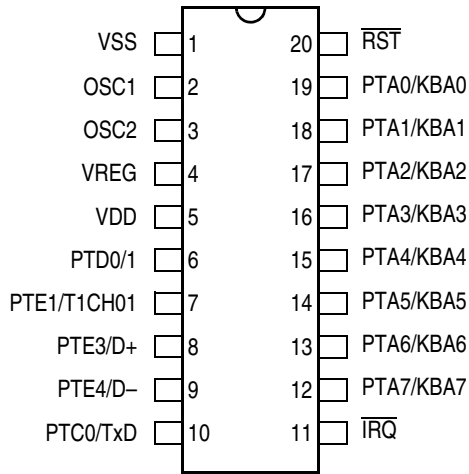
*To:*

$V_{REG}$ LVI trip point voltage	$V_{LVR}$	<b>1.9</b>	2.2	2.6	V
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20-Pin SOIC

Order Number: MC68HC908JB16JDW



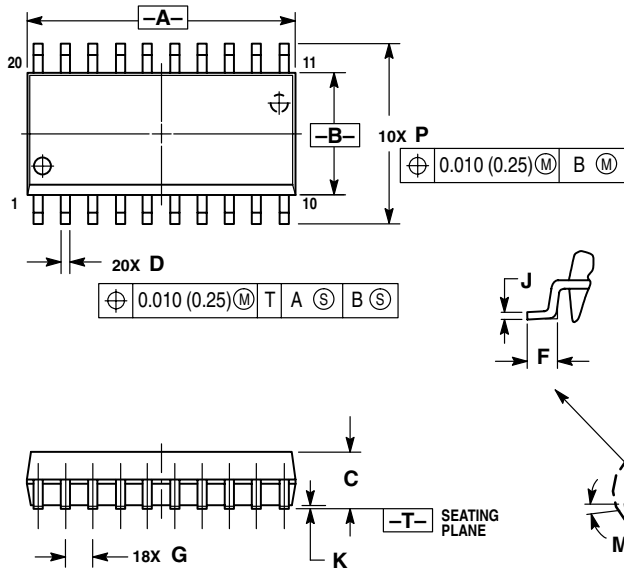
Pins not available on 20-pin package:

PTC1/RxD	PTE0/TCLK	PTD2
	PTE2/T2CH01	PTD3
CGMXFC1	CGMXFC2	PTD4
CGMOUT1	CGMOUT2	PTD5
VREGA0	VREGA1	
VSSA0	VSSA1	VDDA

Internal pads are unconnected.

PTD0/1 pin: PTD0 and PTD1 internal pads are bonded together to PTD0/1 pin, and has 50mA sink capability when configured as an output. Pin direction must be configured such that DDRD0 = DDRD1.

Figure 1. 20-Pin SOIC Pin Assignment



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

Figure 2. 20-Pin SOIC Mechanical Dimensions (Case No. 751D)

**MC68HC908JB12**

This section introduces the MC68HC908JB12, a derivative of the MC68HC908JB16. The entire MC68HC908JB16 data book, including the updates in this addendum, applies to this device, with exceptions outlined below.

**Table 1. Summary of MC68HC908JB12 and MC68HC908JB16 Differences**

	<b>MC68HC908JB12</b>	<b>MC68HC908JB16</b>
<b>FLASH Memory</b>	12,288 bytes (\$CA00–\$F9FF)	16,384 bytes (\$BA00–\$F9FF)
<b>Dual Clock Generator Module</b>	Not implemented. \$0051–\$0059 unimplemented.	Available in 32-pin LQFP only.
<b>Available Packages<sup>(1)</sup></b>	— 28-pin SOIC 20-pin SOIC	32-pin LQFP 28-pin SOIC 20-pin SOIC

**Notes:**

1. The pin assignments are identical for both devices; see data sheet.

**MCU Block Diagram**     **Figure 3** shows the structure of the MC68HC908JB12.

**Memory Map**             **Figure 4** shows the memory map of the MC68HC908JB12.

**Dual Clock Generator Module**     The dual 27-MHz clock generator module on the MC68HC908JB16 is not designed in the MC68HC908JB12, hence, register locations from \$0051 to \$0059 are unimplemented. Information in the data book relating to the CGM do not apply to the MC68HC908JB12.

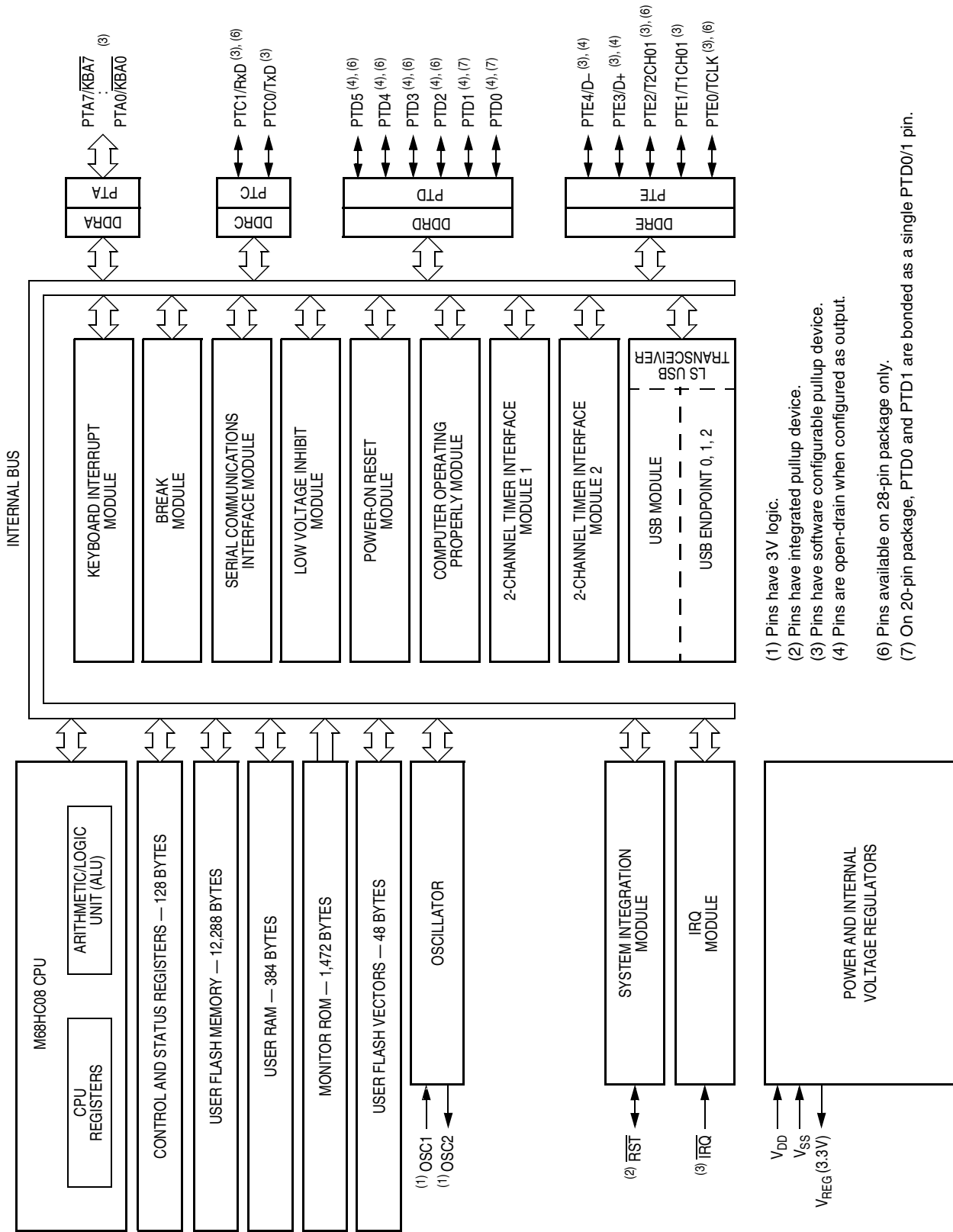


Figure 3. MC68HC908JB12 Block Diagram

\$0000 ↓ \$007F	I/O Registers 128 Bytes
\$0080 ↓ \$01FF	RAM 384 Bytes
\$0200 ↓ \$C9FF	Unimplemented 51,200 Bytes
\$CA00 ↓ \$F9FF	FLASH Memory 12,288 Bytes
\$FA00 ↓ \$FDFE	Monitor ROM 1 1,024 Bytes
\$FE00	SIM Break Status Register (SBSR)
\$FE01	SIM Reset Status Register (SRSR)
\$FE02	Reserved
\$FE03	SIM Break Flag Control Register (SBFCR)
\$FE04	Interrupt Status Register 1 (INT1)
\$FE05	Interrupt Status Register 2 (INT2)
\$FE06	Reserved
\$FE07	Reserved
\$FE08	FLASH Control Register (FLCR)
\$FE09	FLASH Block Protect Register (FLBPR)
\$FE0A	Reserved
\$FE0B	Reserved
\$FE0C	Break Address Register High (BRKH)
\$FE0D	Break Address Register Low (BRKL)
\$FE0E	Break Status and Control Register (BRKSCR)
\$FE0F	Reserved
\$FE10 ↓ \$FFCF	Monitor ROM 2 448 Bytes
\$FFD0 ↓ \$FFFF	FLASH Vectors 48 Bytes

**Figure 4. MC68HC908JB12 Memory Map**

**Pullup on PTE3/D+ and PTE4/D– Pins**

On the MC68HC908JB12, control over the pullup devices on PTE3/D+ and PTE4/D– pins are shown in [Table 2](#).

**Table 2. Pullup Control on PTE3/D+ and PTE4/D– Pins**

PULLEN (\$001A)	USBEN (\$0038)	PTExP (\$001D)	PTE4IE (\$001C)	PTE3/D+ pin	PTE4/D– pin
0	0	0	0	—	—
0	0	1	0	5kΩ pullup to V <sub>DD</sub>	5kΩ pullup to V <sub>DD</sub>
0	0	0	1	—	5kΩ pullup to V <sub>DD</sub> <sup>(1)</sup>
0	0	1	1	5kΩ pullup to V <sub>DD</sub>	5kΩ pullup to V <sub>DD</sub> <sup>(1)</sup>
0	1	X	X	—	—
1	1	X	X	—	1.5kΩ pullup to V <sub>REG</sub>
1	0	X	0	—	1.5kΩ pullup to V <sub>REG</sub>
1	0	X	1	Do not set this configuration.	

**Notes:**

- External interrupt function is also enabled on PTE4/D– pin.

**Electrical Specifications**

Electrical specifications for the MC68HC908JB16 apply to the MC68HC908JB12, except for the USB reset timing:

Bus State	Signaling Levels	
	Transmit	Receive
Reset	NA	D+ and D– < V <sub>IL</sub> (max) for ≥ 8μs (MC68HC908JB16) D+ and D– < V <sub>IL</sub> (max) for ≥ 125μs (MC68HC908JB12)

**Order Numbers**

These are MC order numbers for MC68HC908JB12.

**Table 3. MC68HC908JB12 Order Numbers**

MC Order Number	Package	Operating Temperature Range
MC68HC908JB12JDW	20-pin SOIC	0 °C to +70 °C
MC68HC908JB12DW	28-pin SOIC	0 °C to +70 °C

**MC68HC08JB16**

This section introduces the MC68HC08JB16, the ROM part equivalent to the MC68HC908JB16. The entire MC68HC908JB16 data book applies to this ROM device, with exceptions outlined below.

**Table 4. Summary of MC68HC08JB16 and MC68HC908JB16 Differences**

	<b>MC68HC08JB16</b>	<b>MC68HC908JB16</b>
<b>Memory (\$BA00–\$F9FF)</b>	16,384 bytes ROM	16,384 bytes FLASH
<b>User vectors (\$FFD0–\$FFFF)</b>	48 bytes ROM	48 bytes FLASH
<b>Registers at \$FE08 and \$FE09</b>	Not used; locations are reserved	FLASH related registers. \$FE08 — FLCR \$FE09 — FLBPR
<b>Monitor ROM 1 (\$FA00–\$FDFF)</b>	Unimplemented	Used for testing and FLASH programming/erasing.
<b>Monitor ROM 2 (\$FE10–\$FFCF)</b>	Used for testing purposes only.	
<b>Dual Clock Generator Module</b>	Currently not available.	Available in 32-pin LQFP only.
<b>Available Packages<sup>(1)</sup></b>	32-pin LQFP currently not available. 28-pin SOIC 20-pin SOIC	32-pin LQFP 28-pin SOIC 20-pin SOIC

**Notes:**

1. The pin assignments are identical for both devices; see data sheet.

**MCU Block Diagram**     **Figure 5** shows the block diagram of the MC68HC08JB16.

**Memory Map**     **Figure 6** shows the memory map of the MC68HC08JB16.

**Reserved Registers**     The two registers at \$FE08 and \$FF09 are reserved locations on the MC68HC08JB16.  
  
On the MC68HC908JB16, these two locations are the FLASH control register and the FLASH block protect register respectively.

**Monitor ROM**     The monitor program (monitor ROM, \$FE10–\$FFCF) on the MC68HC08JB16 is for device testing only.

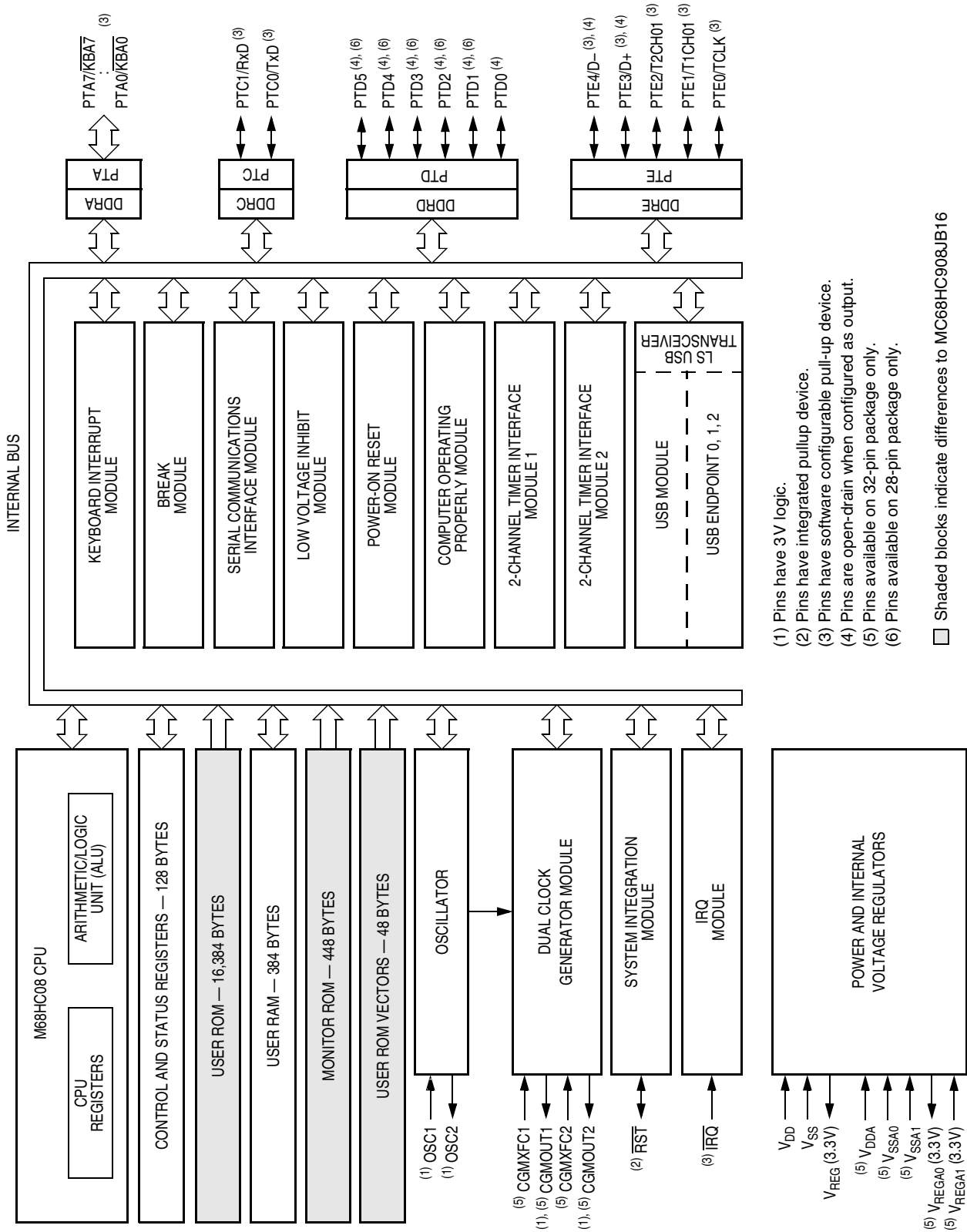


Figure 5. MC68HC908JB16 Block Diagram



\$0000 ↓ \$007F	I/O Registers 128 Bytes
\$0080 ↓ \$01FF	RAM 384 Bytes
\$0200 ↓ \$B9FF	Unimplemented 47,104 Bytes
\$BA00 ↓ \$F9FF	ROM 16,384 Bytes
\$FA00 ↓ \$FDFF	Unimplemented 1,024 Bytes
\$FE00	SIM Break Status Register (SBSR)
\$FE01	SIM Reset Status Register (SRSR)
\$FE02	Reserved
\$FE03	SIM Break Flag Control Register (SBFCR)
\$FE04	Interrupt Status Register 1 (INT1)
\$FE05	Interrupt Status Register 2 (INT2)
\$FE06	Reserved
\$FE07	Reserved
\$FE08	Reserved
\$FE09	Reserved
\$FE0A	Reserved
\$FE0B	Reserved
\$FE0C	Break Address Register High (BRKH)
\$FE0D	Break Address Register Low (BRKL)
\$FE0E	Break Status and Control Register (BRKSCR)
\$FE0F	Reserved
\$FE10 ↓ \$FFCF	Monitor ROM 448 Bytes
\$FFD0 ↓ \$FFFF	ROM Vectors 48 Bytes

**Figure 6. MC68HC08JB16 Memory Map**

### Electrical Specifications

Electrical specifications for the MC68HC908JB16 apply to the MC68HC08JB16, except for the following:

### FLASH Memory Characteristics

The FLASH memory electrical characteristics do not apply to the MC68HC08JB16 ROM device.

### ROM MC Order Numbers

These part numbers are generic numbers only. To place an order, ROM code must be submitted to the ROM Processing Center (RPC).

**Table 5. ROM MC Order Numbers**

MC Order Number	Package	Operating Temperature Range
MC68HC08JB16JDW	20-pin SOIC	0 °C to +70 °C
MC68HC08JB16DW	28-pin SOIC	0 °C to +70 °C

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**NOTES**

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